

CLAIM AMENDMENTS

1. (Currently Amended) A heatsink for an electronic component comprising:
a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at respective angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein
the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins, and

each heat-dissipating portion of each heatsink plate has one separating protrusion which contacts the heat-dissipating portion of an adjacent heatsink plate so that the heat-dissipating portion of each heatsink plate is displaced at an angle from the heat-dissipating portions of adjacent heatsink plates.

Claim 2 (Cancelled).

3. (Currently Amended) The heatsink of claim 1, wherein the binding portions of individual heatsink plates have at least one pair of a binding protrusion and ~~an~~ a binding indentation which are complementary and engaged with a ~~protrusion~~ binding indentation and ~~an indentation~~ a binding protrusion, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

Claim 4 (Cancelled).

5. (Withdrawn) The heatsink of claim 1, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates.

Claim 6 (Cancelled).

7. (Withdrawn-Currently Amended) The heatsink of claim 5, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a binding protrusion and ~~an~~ a binding indentation which are complementary with a ~~protrusion binding indentation and an indentation~~ a binding protrusion, respectively, of another heatsink plate, for preventing distortion of the binding portions.

Claim 8 (Cancelled).

9. (Original) The heatsink of claim 1, comprising a fan installed at the heatsink to blow air over the heatsink.

Claim 10 (Cancelled).

11. (Original) The heatsink of claim 3, comprising a fan installed at the heatsink to blow air over the heatsink.

12. (Withdrawn) The heatsink of claim 1, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

Claim 13 (Cancelled).

14. (Withdrawn) The heatsink of claim 3, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

15. (Currently Amended) A heatsink for an electronic component comprising:
a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at respective angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heat-dissipating fin in the heat-dissipating portion of each heatsink plate has a separating protrusion contacting an adjacent heat-dissipating fin and of a heat-dissipating portion of an adjacent heatsink plate, displacing the heat-dissipating ~~plate fin~~ fin from ~~the heat-dissipating fins of adjacent heat-dissipating plate heatsink plates~~.

16. (Original) The heatsink of claim 15 wherein the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins.

17. (Currently Amended) The heatsink of claim 15, wherein the binding portions of individual heatsink plates have at least one pair of a binding protrusion and an a binding indentation which are complementary and engaged with ~~a protrusion binding indentation and an indentation~~ a binding protrusion, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

18. (Withdrawn) The heatsink of claim 15, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.

Claim 19 (Cancelled).

20. (Withdrawn-Currently Amended) The heatsink of claim 18, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a binding protrusion and an a binding indentation which are complementary with a ~~protrusion binding indentation and an indentation~~ a binding protrusion, respectively, of another heatsink plate, for preventing distortion of the binding portions.

21. (Currently Amended) A heatsink for an electronic component comprising:
a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-

dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at respective angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heat-dissipating portion of an individual heatsink plate has ~~one~~ a separating protrusion which contacts the heat-dissipating portion of an adjacent ~~heat-dissipating heatsink~~ plate so that ~~each~~ the heat-dissipating portion of each heatsink plate is displaced at an angle from ~~adjacent the heat-dissipating portions of adjacent heatsink plates in the heatsink.~~

Claim 22 (Cancelled).

23. (Withdrawn) A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions;

means for binding the plurality of heatsink plates together; and

a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.

24. (Withdrawn) The heatsink of claim 5, wherein the spacers have extensions extending from the plurality of binding portions.